

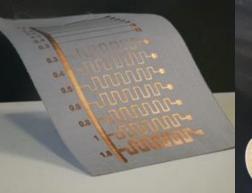
**Additive** technology



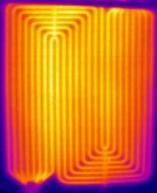
**Flexible** materials



**Copper tracks for High conductivity** 







# PROCESS<br/>IN 3 STEPS



01

# EOPROM® PASTE DEPOSIT

Printing / Screening Spraying / R2R

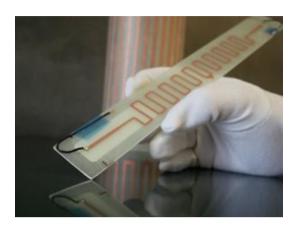
DRYING & CURING

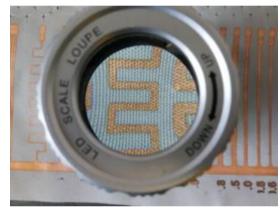
PLATING BATHS
Electroless &
Electrochemical copper,
Ni, Sn, Au







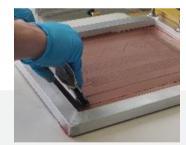






## **EOPROM®:**THE ADHESION

A primary coat using a metal loads based formulation provides exceptional adhesion strength on many substrates. The metal reinforcement permits a wide range of conductivity



# INDUSTRIAL & ECOFRIENDLY PROCESS

This material is low cost (copper based). The process is fully additive, with low environmental impact and designed for mass production



#### ON COMPOSITES AND PLASTICS

Deposits are possible on POLYESTER / FIBERGLASS / FLAX / BASALT / POLYAMID ... Fiberglass prepregs are functionalized before thermoforming



### FLEXIBLE AND MULTI-APPLICATION

EOPROM® paste can be applied on flexible or rigid substrates for a wide range of applications:

- Heating circuit
- Sensors, PZE
- Antenna
- Wiring
- Electronic circuit
- Components soldering



